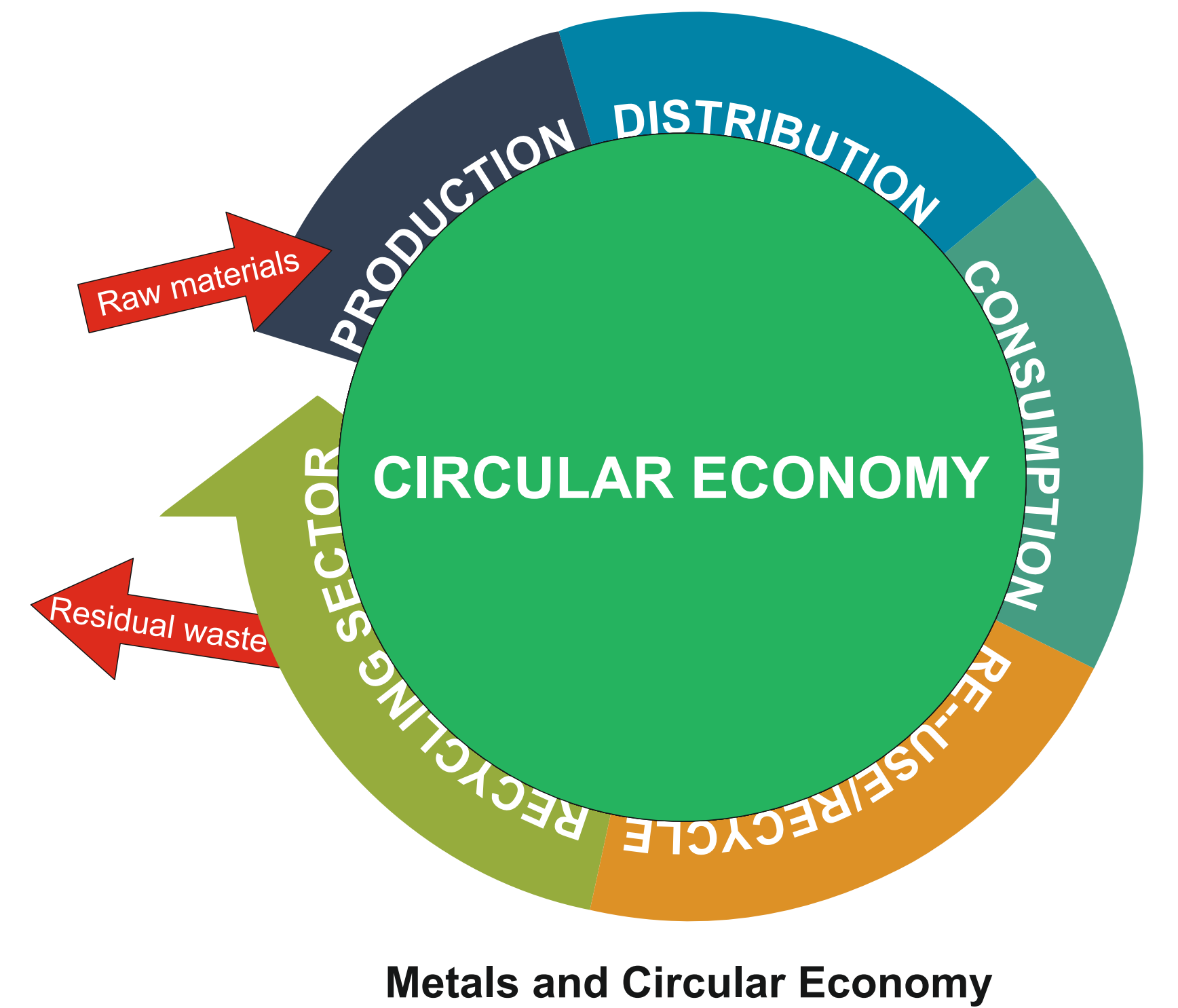
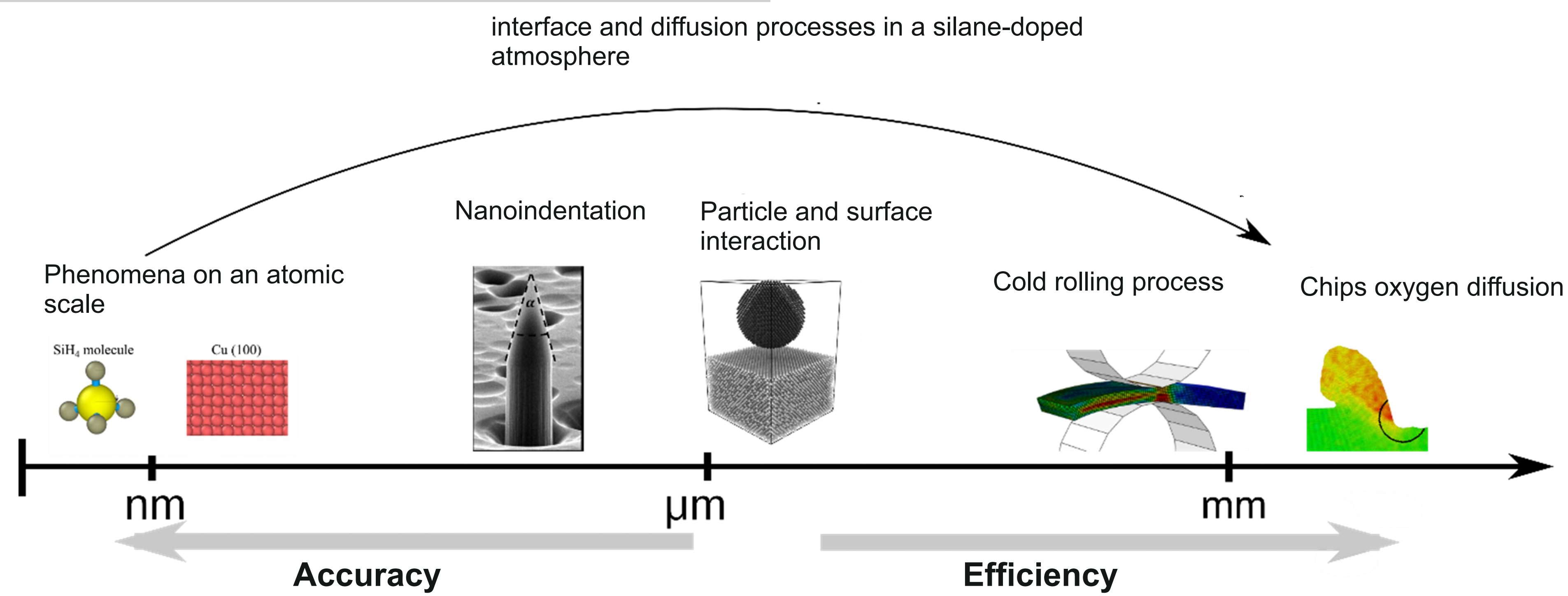


Abstract

Metal products have the potential to undergo mechanical treatment and recycle back into the production process, which allows for the manufacturing of new materials and participating a significant role in the circular economy. The initial step in the circular economy is production, whereas the last and least effective phase is metal recycling. In addition to helping to raise recycled content, efficient **oxidation free production** also raise the rate of end-of-life recycling. This is particularly important when a varied combination of components is highly desired in modern products. By using molecular dynamics simulations, we have the opportunity to gain insight into the essential role of oxide reduction in the atmosphere and on the material surface before and during the production. Beyond being of better quality, products that absence of impurities including oxides also help cut down on waste and raw materials, as well as the cost of recycling.



Validation of simulation models



MD simulations were performed at various scales in cooperation with other experimental specialists.

Validation of the force field for MD simulations

- Suitable interatomic potentials for modeling various processes of oxygen-free production were investigated.
- Surface interfacial phenomena and mechanical processes at the atomic level were implemented and the results carefully examined.

Interface phenomena during joining

The behavior of the oxide layer

- Nanoindentation simulations on Al covered by a native oxide layer lead to plastic deformation in the Al substrate.
- If the deformation is large enough, the oxide layer breaks and cracks appear

Insights into Al and Cu diffusion under oxidation-free conditions

- MD simulations show that diffusion at the oxide-free Cu-Al interface occurs within 1 ns.
- The results are in great agreement with the Gunner-Preston theory (GP zone).
- Heterogeneous diffusion processes are observed, leading to the formation of Al_2Cu or a eutectic ($Al_2Cu + Al$) as indicate primary phase.

Outstanding phenomena Interface phenomena during joining - MD prediction	Schematic representation of the bond formation at the Al/Cu interface
<p>Oxid film Connected partner Breaking up the oxide layer</p>	<p>Al oxide film Cu oxide film Breaking up the oxide layer</p>
<p>Misfit dislocation networks Misfit offset of the Cu/Al interface</p>	<p>Direct contact between AlCu Deformation of the surface</p>
<p>Dislocation accumulations in the Al single crystal Local plasticity, dislocation accumulations</p>	<p>Plastic deformation in aluminium</p>
<p>Cu clusters diffuse into Al, resulting in Al_2Cu Diffusion at the solid body-solid body interface</p>	<p>Al_2Cu- Eutektikum ($Al_2Cu + Al$)-Cluster Formation of Al_2Cu</p>

Insights into the bond formation of Cu and Al (solid-solid) during the joining process. Left) MD prediction, right) Schematic of the joining process.